



2.0A SURFACE MOUNT FAST GLASS PASSIVATED BRIDGE RECTIFIER

Product Summary (@TA = +25°C)

V _{RRM} (V)	I ₀ (A)	V _F (V)	I _R (μA)
200, 400, 600, 800, 1000	2.0	1.3	5

Features and Benefits

- Glass Passivated Die Construction
- Miniature Surface Mount Package Saves Space on PC Boards
- High Current Capability
- Fast Reverse Recovery Time Suitable for High Frequency Applications
- Low Forward Voltage Drop
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Description and Applications

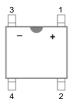
Suitable for AC to DC bridge full wave rectification for SMPS, LED lighting, adapter, battery charger, home appliances, office equipment, and telecommunication applications.

Mechanical Data

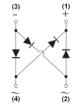
- Case: SOPA-4 (Type B)
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Lead Free Plating (Matte Tin Finish). Solderable per MIL-STD-202, Method 208 (3)
- Polarity: As marked on Body
- Weight: 0.089 grams (Approximate)







Pin Diagram



Internal Schematic

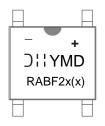
Ordering Information (Note 4)

Part Number	Compliance	Case	Packaging
RABF210-13	Commercial	SOPA-4 (Type B)	5,000/Tape & Reel
RABF28-13	Commercial	SOPA-4 (Type B)	5,000/Tape & Reel
RABF26-13	Commercial	SOPA-4 (Type B)	5,000/Tape & Reel
RABF24-13	Commercial	SOPA-4 (Type B)	5,000/Tape & Reel
RABF22-13	Commercial	SOPA-4 (Type B)	5,000/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



D = Day 1 to 9 = 1 to 9; Day 10 to 31 = A to V

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	Ν	D



Maximum Ratings and Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

Characteristic			RABF22	RABF24	RABF26	RABF28	RABF210	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage			200	400	600	800	1000	V
RMS Reverse Voltage			140	280	420	560	700	V
Average Rectified Output Current (Note 5) @ T _C = +100°C			2.0					Α
Non-Repetitive Peak Forward Surge Current, 8.3ms Single Half Sine-Wave Superimposed on Rated Load			60					Α
I ² t Rating for Fusing (1ms < t < 8.3ms)			14.94				A ² S	
Maximum Forward Voltage (Per Element) @I _F = 2.0A		V_{FM}	1.3				V	
Maximum Reverse Recovery Time (Note 6)			150 250 500			00	ns	
Peak Reverse Current $@T_A = +25^{\circ}C$ At Rated DC Blocking Voltage (Note 7) $@T_A = +125^{\circ}C$		I _R	5.0 200				μΑ	
Typical Total Capacitance (Per Element) (Note 8)					17			ns

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Ambient (Note 5) (Per Element)	$R_{\theta JA}$	63	°C/W
Typical Thermal Resistance, Junction to Lead (Per Element)	$R_{\theta JL}$	25	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Notes:

- 5. Device mounted on aluminum substrate PC board with 1.3mm² solder pad.
- Reverse Recovery Test Conditions: I_F = 0.5A, I_R = 1.0A, I_{RR} = 0.25A.
 Short duration pulse test used to minimize self-heating effect.
 Measured at 1.0MHz and applied reverse voltage of 4.0V D.C.



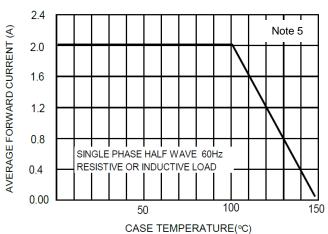


Figure 1. Forward Current Derating

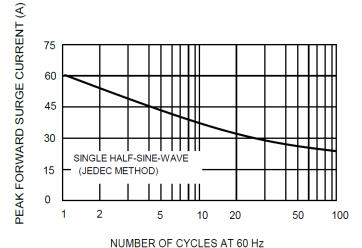
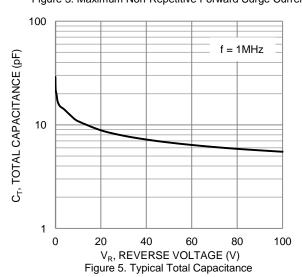
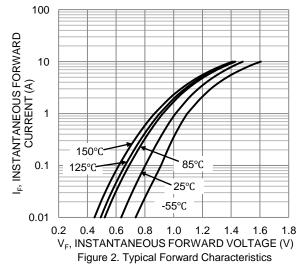


Figure 3. Maximum Non-Repetitive Forward Surge Current





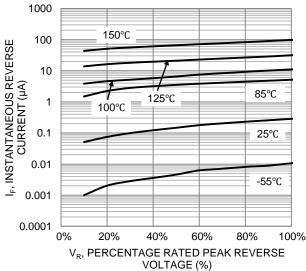


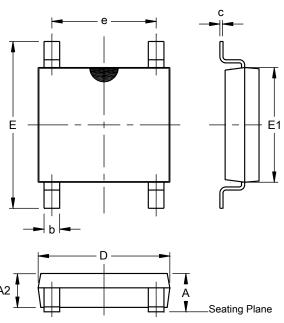
Figure 4. Typical Reverse Characteristics



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOPA-4 (Type B)

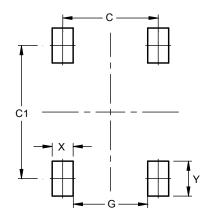


SOPA-4 (Type B)					
Dim	Min	Max	Тур		
Α	1.15	1.30			
A2	1.00	1.25			
b	0.50	0.70			
С	0.15	0.25			
D	4.80	5.30			
Е	6.00	6.80			
E1	4.20	4.60			
е	3.80	4.20			
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOPA-4 (Type B)



Dimensions	Value (in mm)		
С	4.10		
C1	5.72		
G	3.20		
Х	0.90		
V	1.50		



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